

**IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE**

Attorney Docket No.: **TREUSCH - 4**
 TITLE **Stepped Microchannel Heat Sink**
 Application No.:
 Filing Date:
 Group Art Unit:

Commissioner for Patents
 P. O. Box. 1450
 Alexandria, VA 22313-1430

INFORMATION DISCLOSURE STATEMENT

Herewith the Information Disclosure Statement Pursuant to 37 CFR 1.98. Copies of the cited documents are enclosed.

| | Number | Date | Inventor | Assignee | Class | Notes |
|----|---------|------------|-------------|----------------------|----------|---|
| PN | 6480514 | 11/12/2002 | Lorenzon | Jen Optik | 372/35 | μ-ch |
| | 6312166 | 11/06/2001 | Zediker | Nuvonyx | 385/88 | vertical stack array |
| | 6229831 | 05/08/2001 | Nightingale | Coherent | 372/36 | Stepped heat sink |
| | 5987043 | 11/16/1999 | Brown | Opto Power | 372/36 | Stepped heat sink Figs 4-8 |
| | 5848083 | 12/08/1998 | Huden | SDL | 372/36 | Fig. 2E etched channels 134 in sheets 132 |
| | 5212707 | 05/18/1993 | Heidel | McDonnell Douglas | 372/50 | |
| | 5107091 | 04/21/1992 | Wagner | Applied Solar Energy | | μ-ch |
| | 5105430 | 04/14/1992 | Mundinger | US DOE | 372/35 | μ-ch |
| | 5099910 | 03/31/1992 | Walpole | MIT | 165/80.4 | High speed dicing sawed Si (or CuW) μ-ch |
| | 5099311 | 03/24/1992 | Bonde | US DOE | 357/82 | Si μ-ch |
| | 5005640 | 04/09/1991 | Lapinski | McDonnell Douglas | 165.160 | μ-ch grooves sawed plates 4, 16 |
| | 4494171 | 01/15/1985 | Bland | Sunstrand | 361/386 | Diffusion bonded .010 plates, Impingement cooling |
| | 4345643 | 08/24/1982 | Dawson | US DOD | 165/122 | Air-cooled plate array |
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PN DE 2153969 5/1973 Stepped heat sink

PN JP 4-264789 9/1992 Stepped heat sink

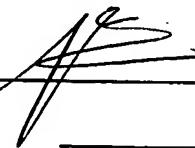
Respectfully,



Howard R. Popper
 Reg. No. 19,208

Attorney for Applicant Dated: September 19, 2003

Examiner:



7/14/05